

Advanced Packaging: Critical Ecosystem and Reliability Considerations

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Outline:

- Advanced Packaging (AP) Overview
- Important Stages & Considerations in the AP Value Stream
 - Wafer Post-Processing and Interconnects
 - Substrates: Boards & Interposers
 - Package Assembly
- Reliability in 2D+ Flip-Chip Packaging
 - Key Processes and Variables
 - Common Failure Modes – Electromigration, Electro-Chemical Migration, Solder Fatigue, and Passivation Failures
- Summary